



HRC0201A

Silicon Schottky Barrier Diode for Rectifying

REJ03G0618-0100
(Previous: ADE-208-1559)
Rev.1.00
May 17, 2005

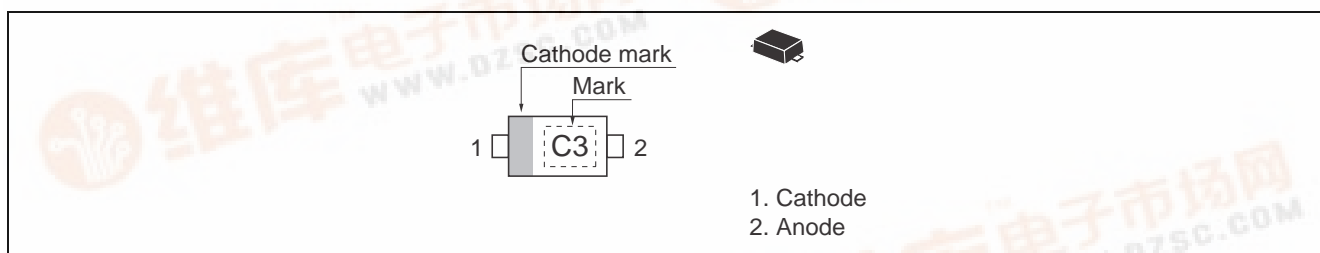
Features

- Low forward voltage drop and suitable for high efficiency rectifying.
- Ultra small Flat Lead Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HRC0201A	C3	UFP	PWSF0002ZA-A (UFP)

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}^{*1}	15	V
Reverse voltage	V_R	15	V
Average rectified current	I_O^{*1}	200	mA
Peak forward current	I_{FM}	300	mA
Non-Repetitive peak forward surge current	I_{FSM}^{*2}	1	A
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Notes: 1. See from Fig.4 to Fig.6, with polyimide board.

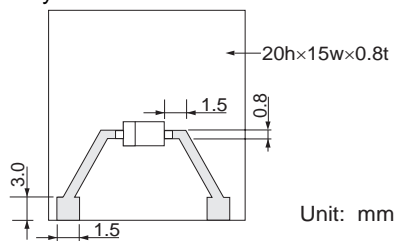
2. 10 ms sine wave 1 pulse.

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_F	—	—	0.39	V	$I_F = 200 \text{ mA}$
Reverse current	I_R	—	—	50	μA	$V_R = 6 \text{ V}$
Capacitance	C	—	18	—	pF	$V_R = 1 \text{ V}, f = 1 \text{ MHz}$
Thermal resistance	$R_{th(j-a)}$	—	600	—	°C/W	Polyimide board *1

Note: 1. Polyimide board



Main Characteristic

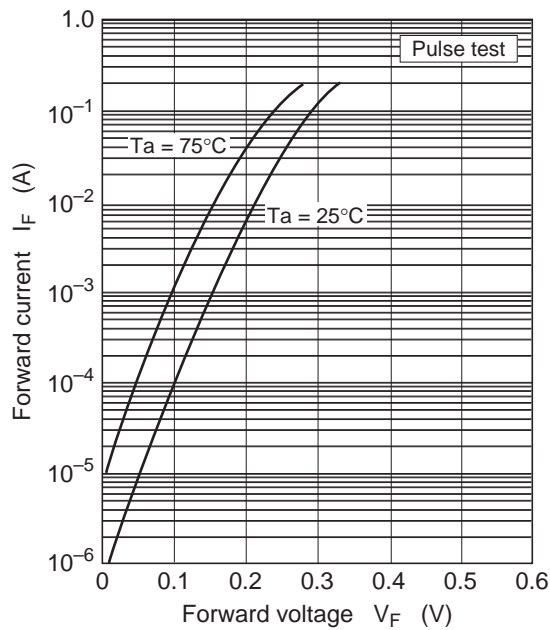


Fig.1 Forward current vs. Forward voltage

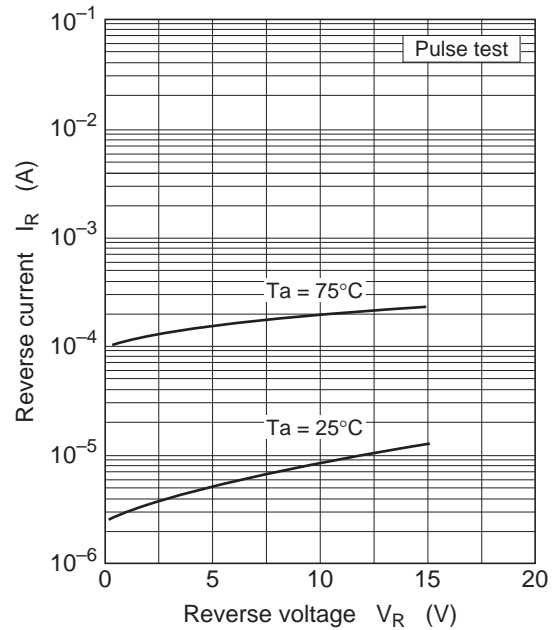


Fig.2 Reverse current vs. Reverse voltage

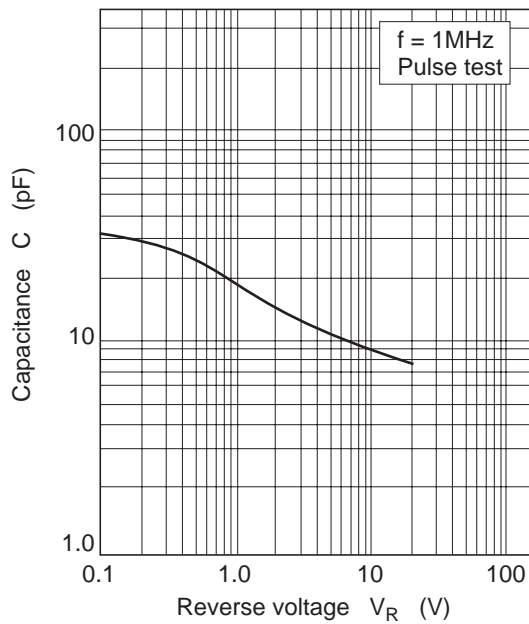


Fig.3 Capacitance vs. Reverse voltage

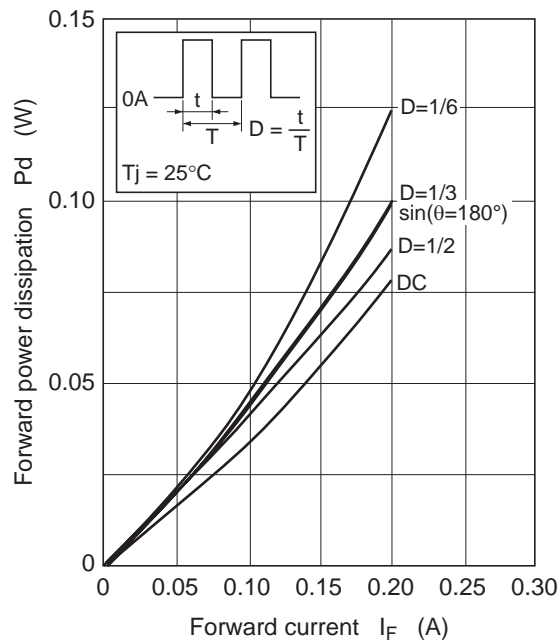


Fig.4 Forward power dissipation vs. Forward current

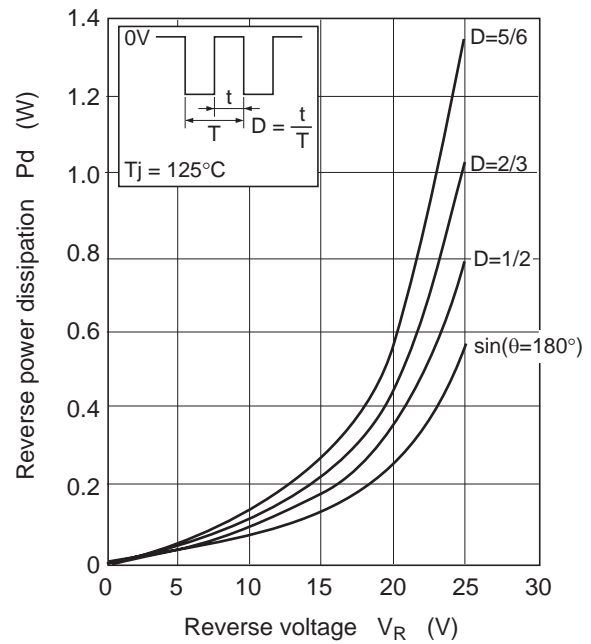


Fig.5 Reverse power dissipation vs. Reverse voltage

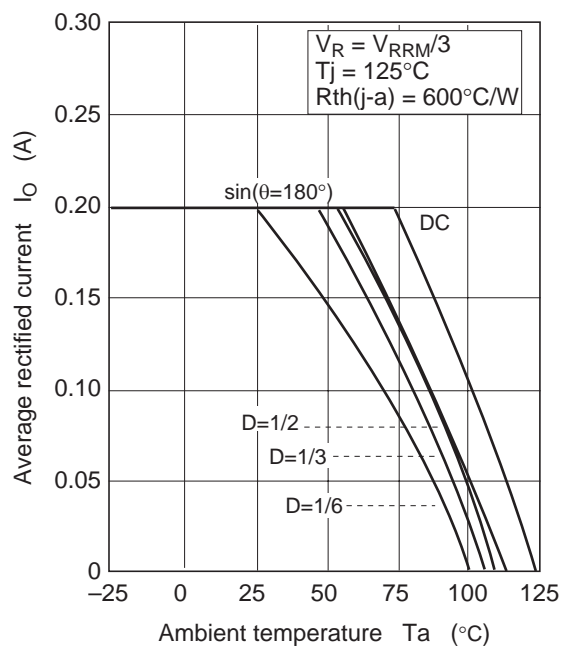
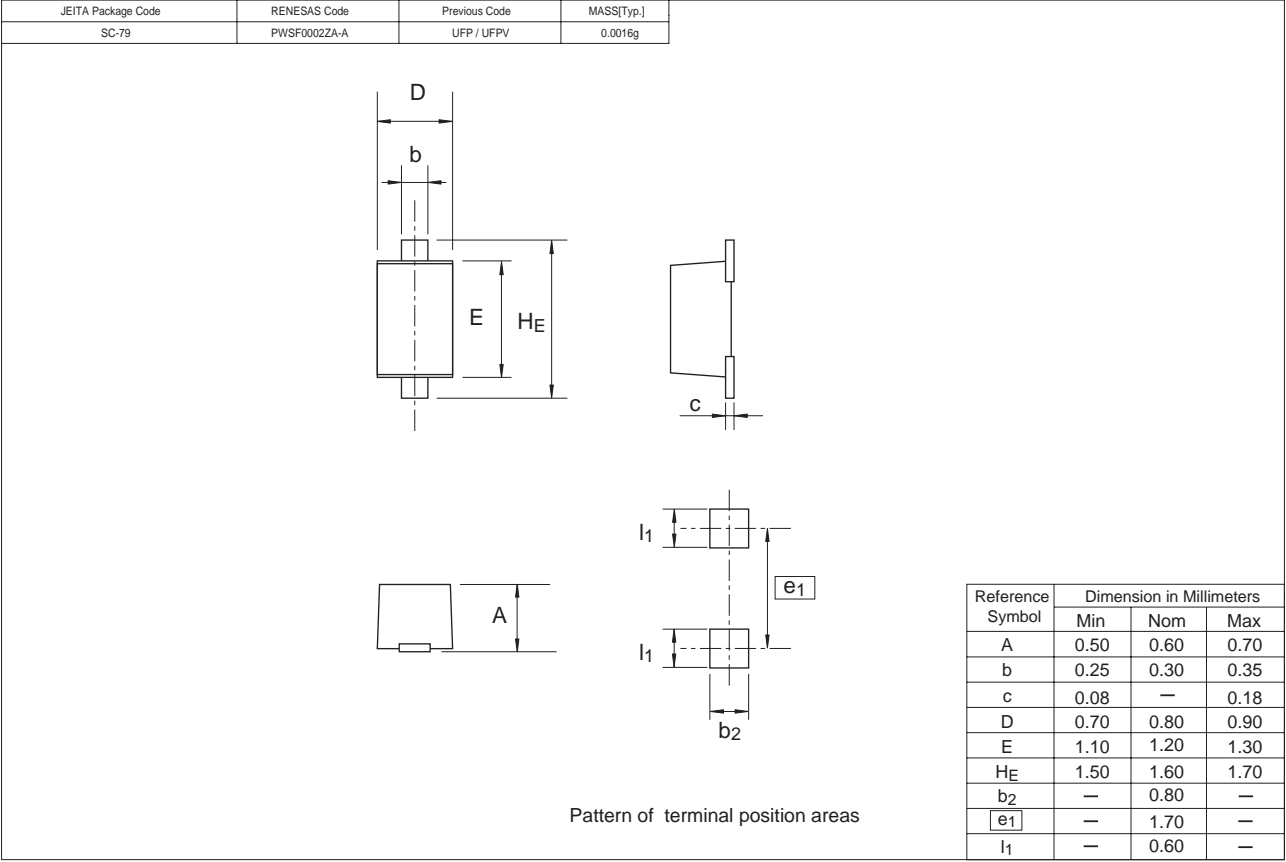


Fig.6 Average rectified current vs. Ambient temperature

Package Dimensions



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